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- ☐ Log-out

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Microelectronic Test Structures, 1990. ICMTS 1990. Proceedings of the 1990 International Conference on , 5-7 Mar 1990

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2 A method for storing fail bit maps in burn-in memory testers

Iseno, A.; Iguchi, Y.;

Electronic Design, Test and Applications, 2002. Proceedings. The First IEEE International Workshop on , 2002

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3 Simulating package behavior under power dissipation using uniform thermal loading

Wakil, J.A.; Ho, P.S.;

Advanced Packaging, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on] , Volume: 24 Issue: 1 , Feb 2001

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Tables of Contents

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

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